



# 中華民國專利證書

發明第 I 690612 號

發明名稱：處理已濺鍍積體電路單元之裝置及方法

專利權人：新加坡商洛克系統私人有限公司

發明人：林仲振、白承昊、丁鍾才、辛彥順、張德春

專利權期間：自 2020 年 4 月 11 日至 2035 年 8 月 12 日止

上開發明業經專利權人依專利法之規定取得專利權

經濟部智慧財產局局長

洪淑敏

中華民國



109

年

4

月

11

日



(Translation)  
**Patent Certificate**  
of  
**The Intellectual Property Office**  
of  
**The Ministry of Economic Affairs**  
Invention Patent No.: I 690612

**Name of Invention** : APPARATUS AND METHOD FOR  
PROCESSING SPUTTERED IC UNITS

**Patentee** : ROKKO SYSTEMS PTE LTD

**Inventors** : LIM, CHONG CHEN, GARY  
BAEK, SEUNG HO  
JUNG, JONG JAE  
SHIN, YUN SUK  
JANG, DEOK CHUN

**Patent Period** : From April 11, 2020  
To August 12, 2035

**Pursuant to Article of the Patent Act, the Patentee acquires the Patent Right.**

(Signature) \_\_\_\_\_  
**Director General : HONG SHU-MIN**

Date : April 11, 2020

Note:

In case the Patentee does not pay the annuity in accordance with the law, the patent right shall be extinguished on the date of expiration of the statutory period for such payment.